

## WHAT IS CLAIMED IS:

1. A polishing composition comprising 0.03 to 0.5% by weight of an organic acid or a salt thereof, an abrasive and water, wherein the abrasive has a surface potential of from -140 to 200 mV.

2. The polishing composition according to claim 1, wherein the organic acid is a polycarboxylic acid having 2 to 10 carbon atoms, having either OH group or groups or SH group or groups.

3. A roll-off reducing agent comprising an inorganic compound having a property of controlling a surface potential of an abrasive in a polishing composition, wherein a surface potential of the abrasive in a standard polishing composition is controlled to -110 to 250 mV by the presence of the inorganic compound, wherein the standard polishing composition is prepared which comprises 20 parts by weight of an abrasive, said abrasive being high-purity alumina having  $\text{Al}_2\text{O}_3$  purity of 98.0% by weight or more composed of  $\alpha$ -type co-random crystal, 1 part by weight of citric acid, 78 parts by weight of water and 1 part by weight of an inorganic compound.

4. The roll-off reducing agent according to claim 3, wherein the inorganic compound is at least one compound selected from the group consisting of a nitrogen-containing inorganic acid or a salt thereof, a sulfur-containing inorganic acid or a salt thereof, a phosphorus-containing inorganic acid or a salt thereof, a halogen-containing inorganic acid or a salt thereof, a carbonate, a cyanate, and a

metal atom-containing inorganic acid or a salt thereof.

5. The roll-off reducing agent according to claim 3 or 4, wherein the inorganic compound is sulfuric acid or a sulfate.

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6. A polishing composition comprising the roll-off reducing agent as defined in claim 3 or 4.

7. The polishing composition according to claim 6, further comprising an abrasive, an organic acid or a salt thereof, and water.

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8. The polishing composition according to claim 1 or 2, wherein the abrasive is alumina.

9. The polishing composition according to claim 7, wherein the abrasive is alumina.

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10. A process for producing a substrate comprising a step of polishing a substrate to be polished with the polishing composition of claim 1 or 2.

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11. A process for producing a substrate comprising a step of polishing a substrate to be polished with the polishing composition of claim 6.

12. The process according to claim 10, wherein the substrate to be polished is a magnetic disk substrate.

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13. The process according to claim 11, wherein the substrate to be polished is a magnetic disk substrate.
- 5 14. A process of reducing roll-off of a substrate, comprising applying to a substrate to be polished a polishing liquid comprising the roll-off reducing agent as defined in claim 3 or 4 in the polishing step.
- 10 15. A process of reducing roll-off of a substrate, comprising applying to a substrate to be polished the polishing composition as defined in claim 1 or 2 in the polishing step.